

STS9D8NH3LL

Dual N-channel 30 V - 0.012 Ω - 9 A - SO-8 low on-resistance STripFETTM Power MOSFET

Features

Туре		V_{DSS}	R _{DS(on)}	Qg	I _D
STS9D8NH3LL	Q_1	30V	< 0.022Ω	7nC	8A
OTOSBONIOLE	Q_2	30V	< 0.015Ω	8nC	9A

- Optimal R_{DS}(on) x Qg trade-off @ 4.5V
- Conduction losses reduced
- Switching losses reduced

Application

■ Switching applications

Description

This device uses the latest advanced design rules of ST's STrip based technology. The Q1 and Q2 transistors, show respectively, the best gate charge and on-resistance for minimizing the switching and conduction losses. This application specific Power MOSFET has been designed to replace two SO-8 packages in DC-DC converters.

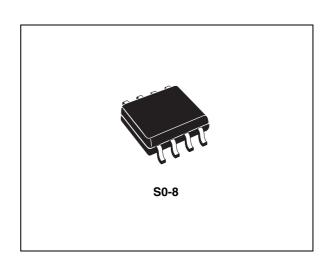


Figure 1. Internal schematic diagram

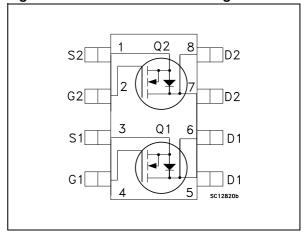


Table 1. Device summary

Order code	Marking	Package	Packaging
STS9D8NH3LL	9D8H3LL-	SO-8	Tape & reel

Contents STS9D8NH3LL

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STS9D8NH3LL Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Туре	Value	Unit
V _{DS}	Drain-source voltage (v _{GS} = 0)	Q ₁ Q ₂	30 30	V V
V _{GS}	Gate- source voltage	Q ₁ Q ₂	±16 ±16	V V
I _D	Drain current (continuous) at T _C = 25°C	Q ₁ Q ₂	8 9	A A
I _D	Drain current (continuous) at T _C = 100°C	Q ₁ Q ₂	5 6.3	A A
I _{DM} ⁽¹⁾	Drain current (pulsed)	Q ₁ Q ₂	32 36	A A
P _{TOT}	Total dissipation at T _C = 25°C	Q ₁ Q ₂	2 2	W W
E _{AS} ⁽²⁾	Single pulse avalanche energy		150	mJ

^{1.} Pulse width limited by safe operating area

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-a} (1)	Thermal resistance junction-ambient max	62.5	°C/W
T_J	Thermal operating junction-ambient	150	°C
T _{stg}	Storage temperature	-55 to 150	°C

^{1.} When mounted on 1 inch² FR-4 board, 2 oz. Cu., $t \le 10s$

^{2.} Starting $T_J = 25$ °C, $I_D = 7.5$ A

Electrical characteristics STS9D8NH3LL

2 Electrical characteristics

(T_{CASE} =25°C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Туре	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	Q ₁ Q ₂	30 30			V V
I _{DSS}	Zero gate voltage Drain current (V _{GS} = 0)	V _{DS} = Max rating	Q ₁ Q ₂			1	μ Α μ Α
I _{DSS}	Zero gate voltage Drain current (V _{GS} = 0)	V _{DS} =Max rating @125°C	Q ₁ Q ₂			10 10	μA μA
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 16 V	Q ₁ Q ₂			±100 ±100	nA nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS},$ $I_D = 250 \mu A$	Q ₁ Q ₂	1			V V
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 4.5 \text{ A}$	Q ₁ Q ₂		0.018 0.012	0.022 0.015	Ω Ω
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 4.5 \text{ A}$	Q ₁ Q ₂		0.020 0.014	0.025 0.0175	Ω Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Туре	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		Q ₁ Q ₂		857 1070		pF pF
C _{oss}	Output capacitance	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz,}$ $V_{GS} = 0$	Q ₁ Q ₂		147 290		pF pF
C _{rss}	Reverse transfer capacitance		Q ₁ Q ₂		20 34		pF pF
Qg	Total gate charge		Q ₁ Q ₂		7 8	10 11	nC nC
Q _{gs}	Gate-source charge	V_{DD} = 15 V, I_{D} = 8 A, V_{GS} = 4.5 V (see Figure 25)	Q ₁ Q ₂		2.5 2		nC nC
Q _{gd}	Gate-drain charge	(655 / igal 5 20)	Q ₁ Q ₂		2.3 2.8		nC nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Туре	Min.	Тур.	Max.	Unit
t _{d(on)}		V _{DD} =15 V, I _D =4 A,	Q ₁		12		ns
, ,	Turn-on delay time	$R_G=4.7 \Omega$	Q_2		8.2		ns
t _r	Rise time	R_{G} =4.7 Ω , V_{GS} = 4.5 V	Q_1		14.5		ns
		(see Figure 27)	Q_2		6		ns
t _{d(off)}		V _{DD} =15 V, I _D =4 A,	Q ₁		23		ns
,	Turn-off delay time	$R_G=4.7 \Omega$	Q_2		27.8		ns
t _f	Fall time	V_{DD} =15 V, I_{D} =4 A, R_{G} =4.7 Ω , V_{GS} = 4.5 V	Q_1		8		ns
		(see Figure 27)	Q_2		3.6		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Туре	Min	Тур.	Max	Unit
I _{SD}	Source-drain current	V_{DD} =15 V, I_{D} =4 A R_{G} =4.7 Ω V_{GS} =4.5 V	Q ₁ Q ₂			8 9	A A
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)	V_{DD} =15 V, I_{D} = 4A R_{G} =4.7 Ω V_{GS} =4.5 V	Q ₁ Q ₂			32 36	A A
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 8 A, V _{GS} = 0	Q ₁ Q ₂			1.5 1.5	V V
t _{rr}	Reverse recovery time Reverse recovery charge	$I_{SD} = 8 \text{ A},$ $V_{DD} = 15 \text{ V}$ $di/dt = 100 \text{ A/}\mu\text{s},$	Q ₁ Q ₂ Q ₁ Q ₂		15 22.8 5.7 14.9		ns ns nC nC
I _{RRM}	Reverse recovery current	$T_j = 150^{\circ}C$ (see Figure 26)	Q_1 Q_2		0.76 1.3		A A

^{1.} Pulse width limited by safe operating area.

^{2.} Pulsed: Pulse duration = 300 μ s, duty cycle 1.5%

Electrical characteristics STS9D8NH3LL

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for Q1

Figure 3. Safe operating area for Q2

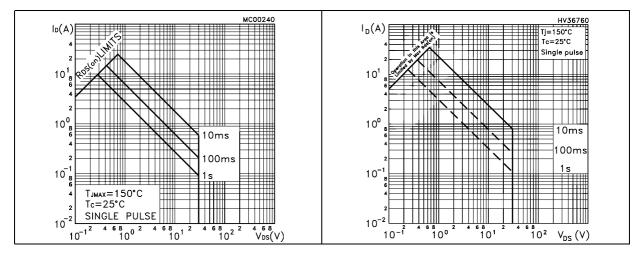


Figure 4. Thermal impedance for Q1

Figure 5. Thermal impedance for Q2

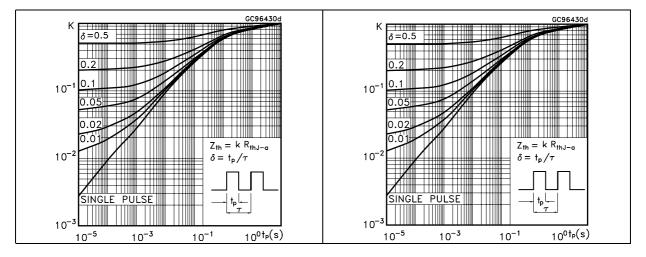
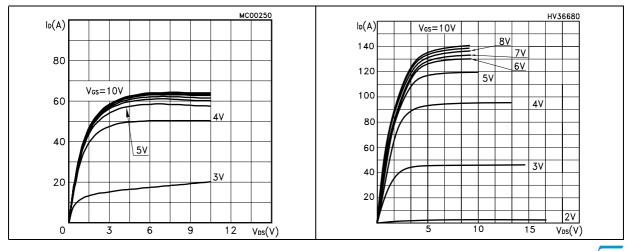


Figure 6. Output characteristics for Q1

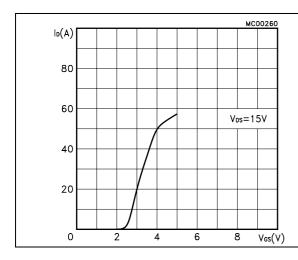
Figure 7. Output characteristics for Q2



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Figure 8. **Transfer characteristics for Q1**

Figure 9. **Transfer characteristics for Q2**



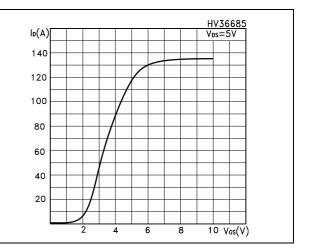
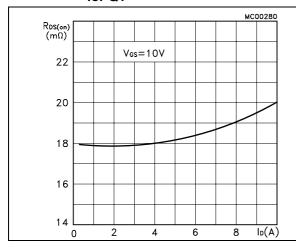
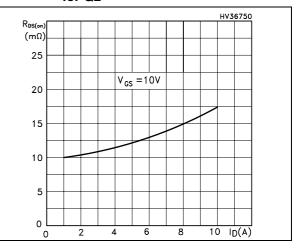


Figure 10. Static drain-source on resistance for Q1

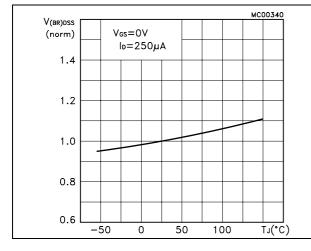
Figure 11. Static drain-source on resistance for Q2

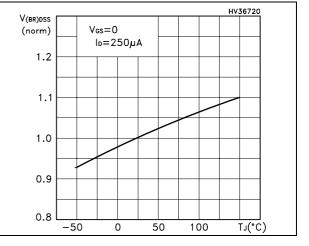




for Q1

Figure 12. Normalized BV_{DSS} vs temperature Figure 13. Normalized BV_{DSS} vs temperature for Q2





Electrical characteristics STS9D8NH3LL

Figure 14. Gate charge vs gate-source voltage Figure 15. Gate charge vs gate-source voltage for Q1 for Q2

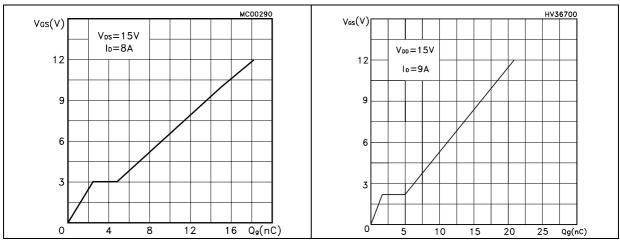


Figure 16. Capacitance variations for Q1

Figure 17. Capacitance variations for Q2

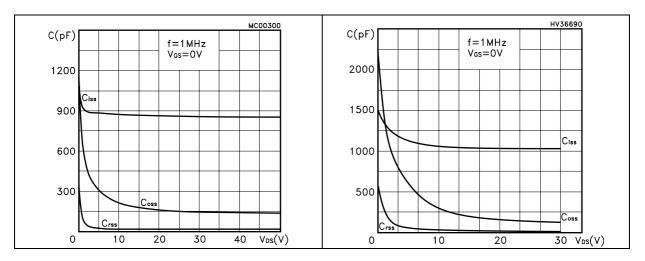
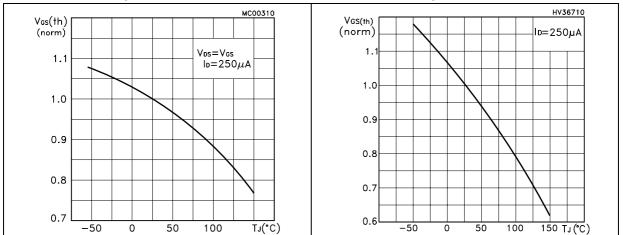


Figure 18. Normalized gate threshold voltage Figure 19. Normalized gate threshold voltage vs temperature for Q1 vs temperature for Q2



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Figure 20. Normalized on resistance vs temperature for Q1

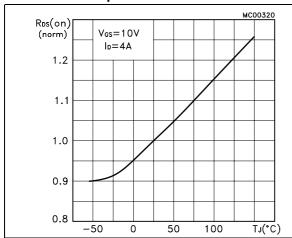


Figure 21. Normalized on resistance vs temperature for Q2

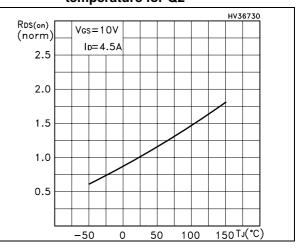


Figure 22. Source-drain diode forward characteristics for Q1

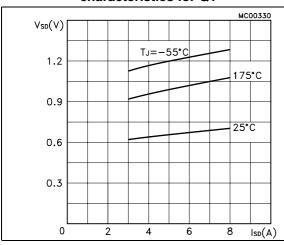
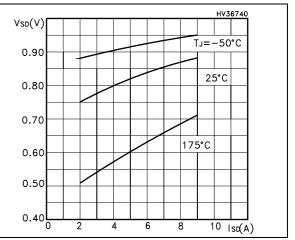


Figure 23. Source-drain diode forward characteristics for Q2



Test circuit STS9D8NH3LL

3 Test circuit

Figure 24. Switching times test circuit for resistive load

Figure 25. Gate charge test circuit

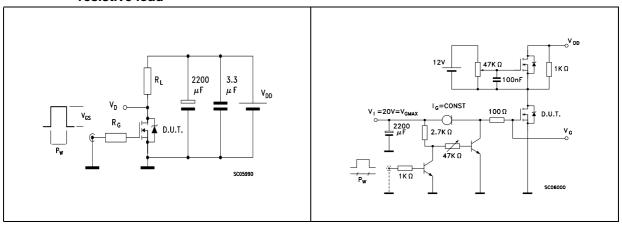


Figure 26. Test circuit for inductive load switching and diode recovery times

Figure 27. Unclamped Inductive load test circuit

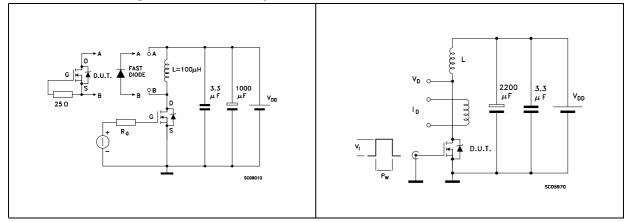
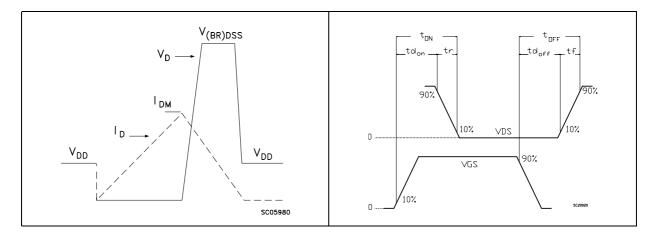


Figure 28. Unclamped inductive waveform

Figure 29. Switching time waveform



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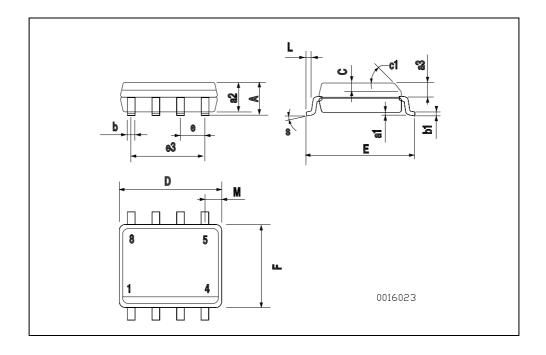
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

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SO-8	MECHANICAL	$D\Delta T\Delta$
30-0		. レヘιヘ

DIM.	mm.				inch	
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
аЗ	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
Е	5.8		6.2	0.228		0.244
е		1.27			0.050	
е3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)	•	•



STS9D8NH3LL Revision history

5 Revision history

Table 8. Document revision history

Date	Revision	Changes
05-Jan-2007	1	First release
06-Mar-2007 2 Some value changed on <i>Table 4</i> (R _{DS(on)} for Q2)		Some value changed on <i>Table 4</i> (R _{DS(on)} for Q2)
10-Dec-2007	3	Added E _{AS} value on <i>Table 2: Absolute maximum ratings</i>

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